

**Amendments to the Abstract**

Please insert the Abstract set forth below immediately following the claims of the subject application:

**ABSTRACT OF THE DISCLOSURE**

A ball grid array package includes a chip having a substrate with a bottom surface, a plurality of solder bumps projecting outwardly from the bottom surface of the substrate, and an electromagnetic shield including a housing that defines an inner space which receives the chip and the solder bumps therein, and a bottom opening for access into the inner space. The solder bumps project outwardly of the inner space through the bottom opening in the housing.